

## 74F373

### Octal Transparent Latch with 3-STATE Outputs

#### General Description

The 74F373 consists of eight latches with 3-STATE outputs for bus organized system applications. The flip-flops appear transparent to the data when Latch Enable (LE) is HIGH. When LE is LOW, the data that meets the setup times is latched. Data appears on the bus when the Output Enable ( $\overline{OE}$ ) is LOW. When  $\overline{OE}$  is HIGH the bus output is in the high impedance state.

#### Features

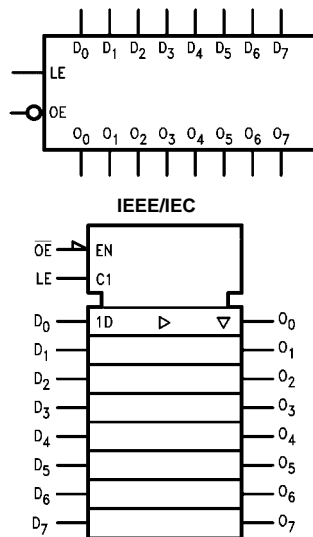
- Eight latches in a single package
- 3-STATE outputs for bus interfacing
- Guaranteed 4000V minimum ESD protection

#### Ordering Code:

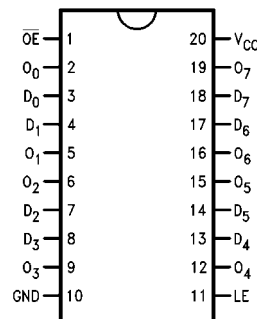
Order Number	Package Number	Package Description
74F373SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F373SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F373MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74F373PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

#### Logic Symbols



#### Connection Diagram



74F373 Octal Transparent Latch with 3-STATE Outputs

### Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input $I_{IH}/I_{IL}$ Output $I_{OH}/I_{OL}$
D <sub>0</sub> –D <sub>7</sub>	Data Inputs	1.0/1.0	20 $\mu$ A/–0.6 mA
LE	Latch Enable Input (Active HIGH)	1.0/1.0	20 $\mu$ A/–0.6 mA
$\overline{OE}$	Output Enable Input (Active LOW)	1.0/1.0	20 $\mu$ A/–0.6 mA
O <sub>0</sub> –O <sub>7</sub>	3-STATE Latch Outputs	150/40 (33.3)	–3 mA/24 mA (20 mA)

### Functional Description

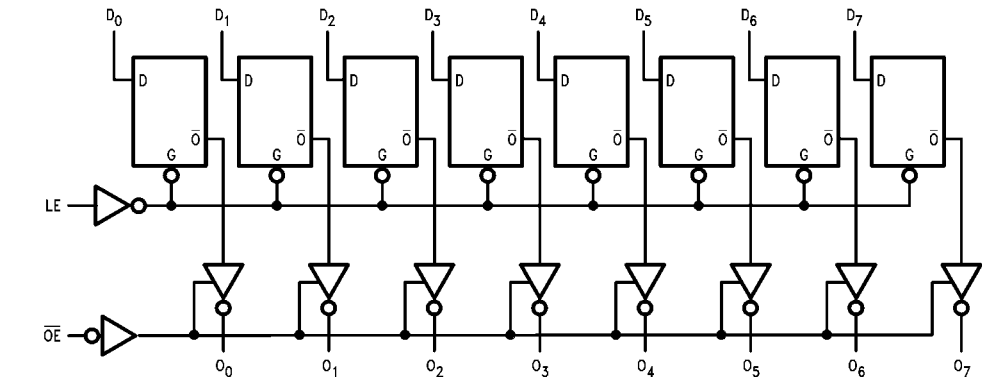
The 74F373 contains eight D-type latches with 3-STATE output buffers. When the Latch Enable (LE) input is HIGH, data on the D<sub>n</sub> inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW, the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-STATE buffers are controlled by the Output Enable ( $\overline{OE}$ ) input. When  $\overline{OE}$  is LOW, the buffers are in the bi-state mode. When  $\overline{OE}$  is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

### Truth Table

Inputs			Output
LE	$\overline{OE}$	D <sub>n</sub>	O <sub>n</sub>
H	L	H	H
H	L	L	L
L	L	X	O <sub>n</sub> (no change)
X	H	X	Z

H = HIGH Voltage Level  
L = LOW Voltage Level  
X = Immaterial  
Z = High Impedance State

### Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

**Absolute Maximum Ratings**(Note 1)

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +150°C
V <sub>CC</sub> Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V <sub>CC</sub> = 0V)	
Standard Output	−0.5V to V <sub>CC</sub>
3-STATE Output	−0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I <sub>OL</sub> (mA)
ESD Last Passing Voltage (Min)	4000V

**Recommended Operating Conditions**

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

**DC Electrical Characteristics**

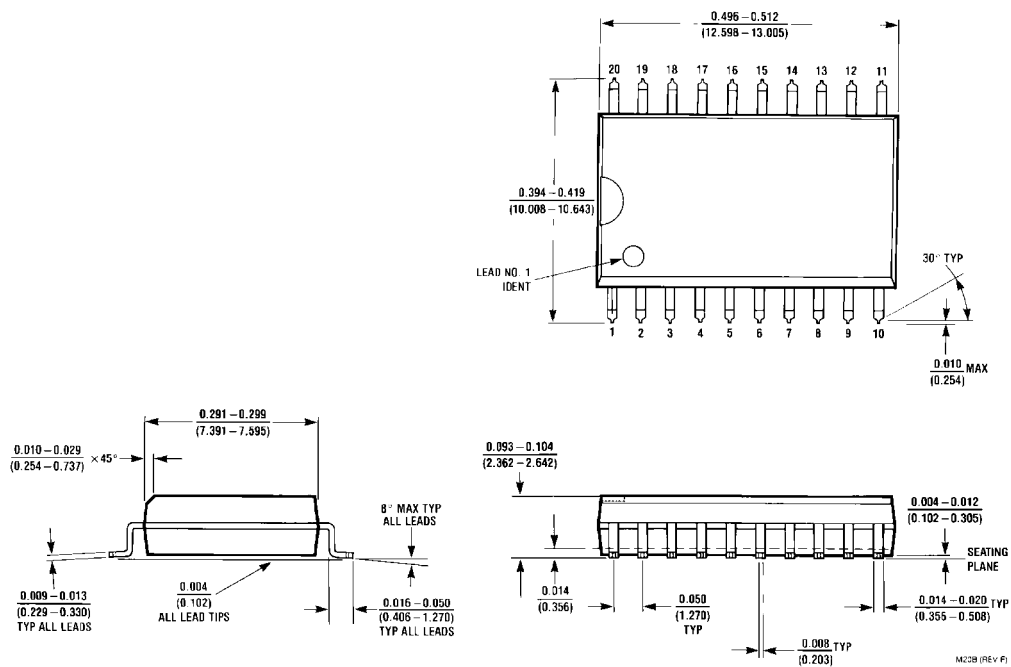
Symbol	Parameter	Min	Typ	Max	Units	V <sub>CC</sub>	Conditions
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V <sub>IL</sub>	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V <sub>CD</sub>	Input Clamp Diode Voltage			−1.2	V	Min	I <sub>IN</sub> = −18 mA
V <sub>OH</sub>	Output HIGH Voltage	10% V <sub>CC</sub> 10% V <sub>CC</sub> 5% V <sub>CC</sub> 5% V <sub>CC</sub>	2.5 2.4 2.7 2.7		V	Min	I <sub>OH</sub> = −1 mA I <sub>OH</sub> = −3 mA I <sub>OH</sub> = −1 mA I <sub>OH</sub> = −3 mA
V <sub>OL</sub>	Output LOW Voltage	10% V <sub>CC</sub>		0.5	V	Min	I <sub>OL</sub> = 24 mA
I <sub>IH</sub>	Input HIGH Current			5.0	μA	Max	V <sub>IN</sub> = 2.7V
I <sub>BVI</sub>	Input HIGH Current Breakdown Test			7.0	μA	Max	V <sub>IN</sub> = 7.0V
I <sub>CEX</sub>	Output HIGH Leakage Current			50	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub>
V <sub>ID</sub>	Input Leakage Test	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA All Other Pins Grounded
I <sub>OD</sub>	Output Leakage Circuit Current			3.75	μA	0.0	V <sub>IOD</sub> = 150 mV All Other Pins Grounded
I <sub>IL</sub>	Input LOW Current			−0.6	mA	Max	V <sub>IN</sub> = 0.5V
I <sub>OZH</sub>	Output Leakage Current			50	μA	Max	V <sub>OUT</sub> = 2.7V
I <sub>OZL</sub>	Output Leakage Current			−50	μA	Max	V <sub>OUT</sub> = 0.5V
I <sub>OS</sub>	Output Short-Circuit Current	−60		−150	mA	Max	V <sub>OUT</sub> = 0V
I <sub>ZZ</sub>	Bus Drainage Test			500	μA	0.0V	V <sub>OUT</sub> = 5.25V
I <sub>CCZ</sub>	Power Supply Current		38	55	mA	Max	V <sub>O</sub> = HIGH Z

## AC Electrical Characteristics

Symbol	Parameter	T <sub>A</sub> = +25°C V <sub>CC</sub> = +5.0V C <sub>L</sub> = 50 pF			T <sub>A</sub> = -55°C to +125°C V <sub>CC</sub> = +5.0V C <sub>L</sub> = 50 pF		T <sub>A</sub> = 0°C to +70°C V <sub>CC</sub> = +5.0V C <sub>L</sub> = 50 pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
t <sub>PLH</sub>	Propagation Delay	3.0	5.3	7.0	3.0	8.5	3.0	8.0	ns
t <sub>PHL</sub>	D <sub>n</sub> to O <sub>n</sub>	2.0	3.7	5.0	2.0	7.0	2.0	6.0	
t <sub>PLH</sub>	Propagation Delay	5.0	9.0	11.5	5.0	15.0	5.0	13.0	ns
t <sub>PHL</sub>	LE to O <sub>n</sub>	3.0	5.2	7.0	3.0	8.5	3.0	8.0	
t <sub>PZH</sub>	Output Enable Time	2.0	5.0	11.0	2.0	13.5	2.0	12.0	ns
t <sub>PZL</sub>		2.0	5.6	7.5	2.0	10.0	2.0	8.5	
t <sub>PHZ</sub>	Output Disable Time	1.5	4.5	6.5	1.5	10.0	1.5	7.5	ns
t <sub>PLZ</sub>		1.5	3.8	5.0	1.5	7.0	1.5	6.0	

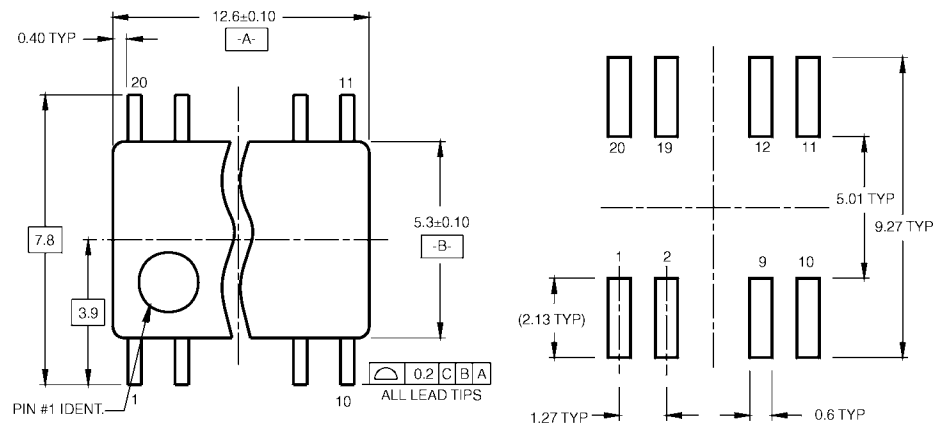
## AC Operating Requirements

Symbol	Parameter	T <sub>A</sub> = +25°C V <sub>CC</sub> = +5.0V		T <sub>A</sub> = -55°C to +125°C V <sub>CC</sub> = +5.0V		T <sub>A</sub> = 0°C to +70°C V <sub>CC</sub> = +5.0V		Units
		Min	Max	Min	Max	Min	Max	
t <sub>S</sub> (H)	Setup Time, HIGH or LOW	2.0		2.0		2.0		ns
t <sub>S</sub> (L)	D <sub>n</sub> to LE	2.0		2.0		2.0		
t <sub>H</sub> (H)	Hold Time, HIGH or LOW	3.0		3.0		3.0		
t <sub>H</sub> (L)	D <sub>n</sub> to LE	3.0		4.0		3.0		ns
t <sub>W</sub> (H)	LE Pulse Width, HIGH	6.0		6.0		6.0		

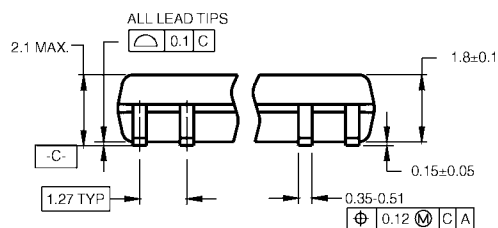
**Physical Dimensions** inches (millimeters) unless otherwise noted


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide  
Package Number M20B**

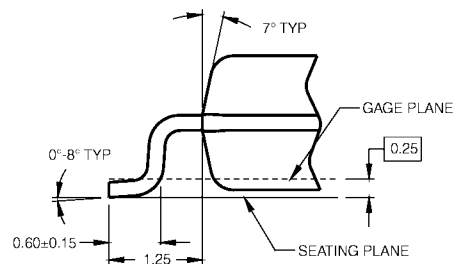
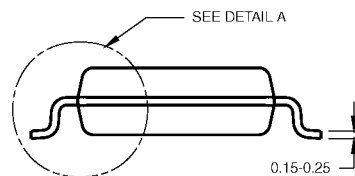
# Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



## LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



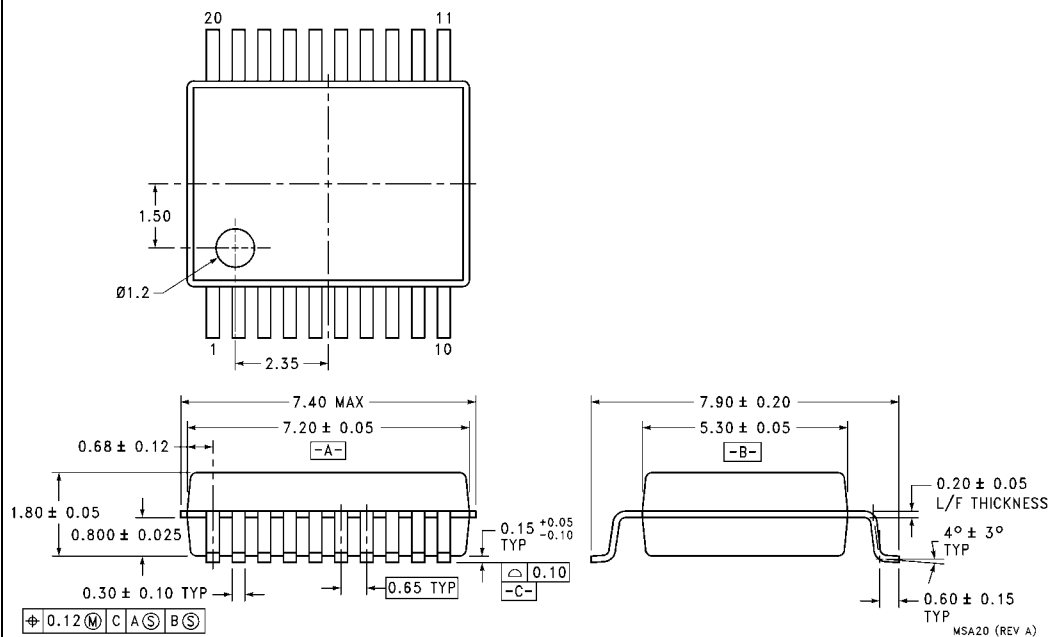
## DETAIL A

### NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

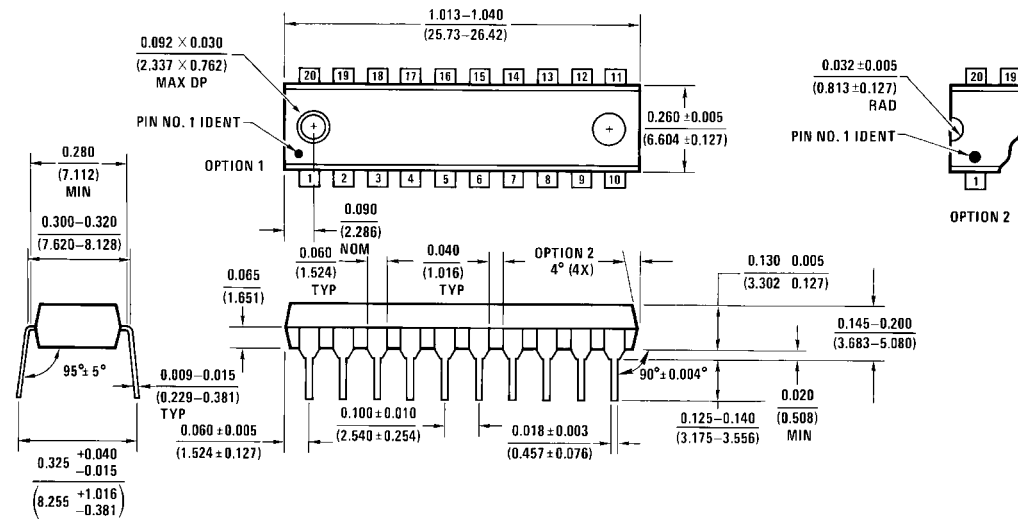
M20DRevB1

**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
Package Number M20D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)


**20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide**  
**Package Number MSA20**

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



N20A (REV G)

20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide  
Package Number N20A

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